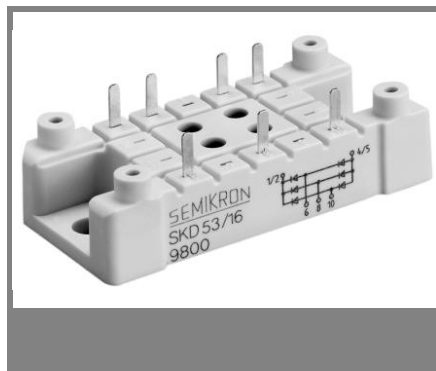




Power Bridge Rectifiers

SKD 33

Features

- Glass passivated silicon chips
- Low thermal impedance through use of direct copper bonded aluminum substrate (DCB) base plate
- Blocking voltage up to 1800 V
- Suitable for PCB mounting and wave soldering
- For applications with high vibrations we recommend to fasten the bridge to the pcb with 4 selftapping screw

Typical Applications

- Three phase rectifiers for power supplies
- Input rectifiers for variable frequency drives
- Rectifiers for DC motor field supplies
- Battery charger rectifiers

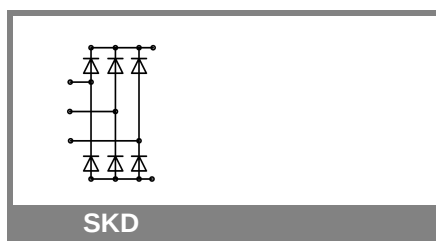
1) Freely suspended or mounted on an insulator

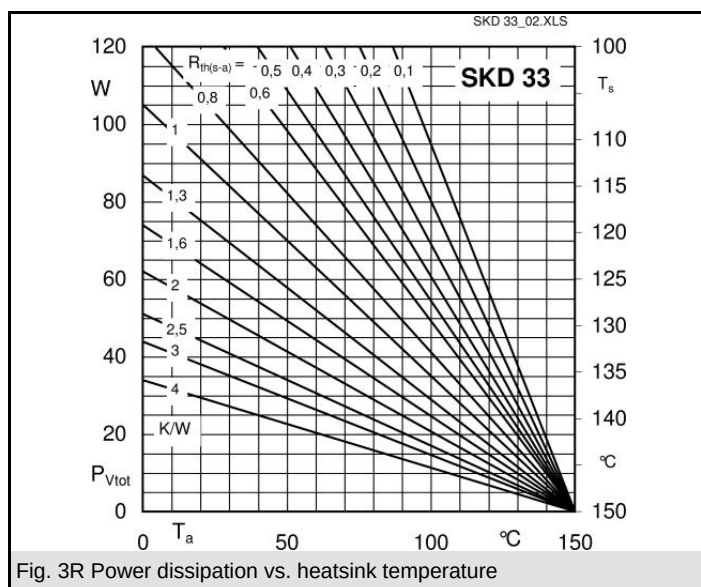
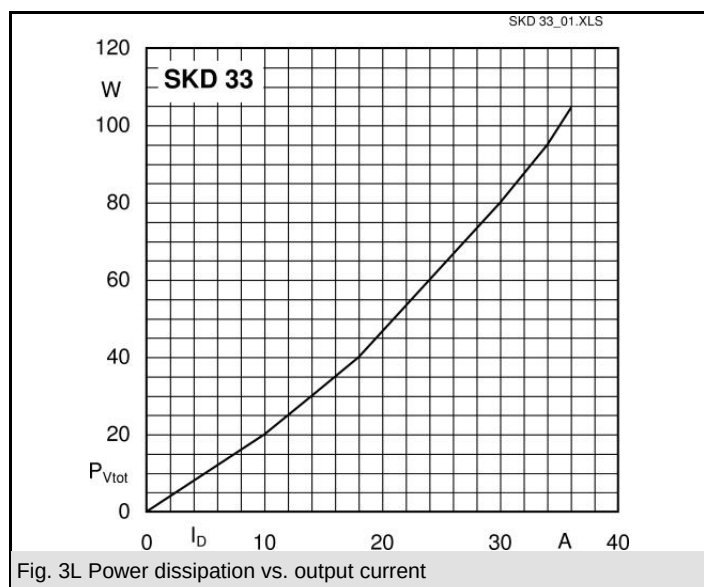
2) Mounted on a painted metal sheet of min. 250 x 250 x 1 mm

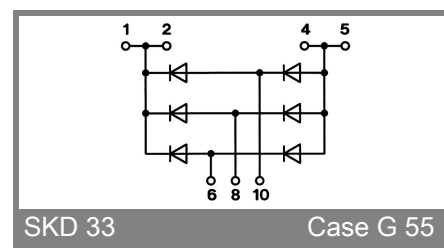
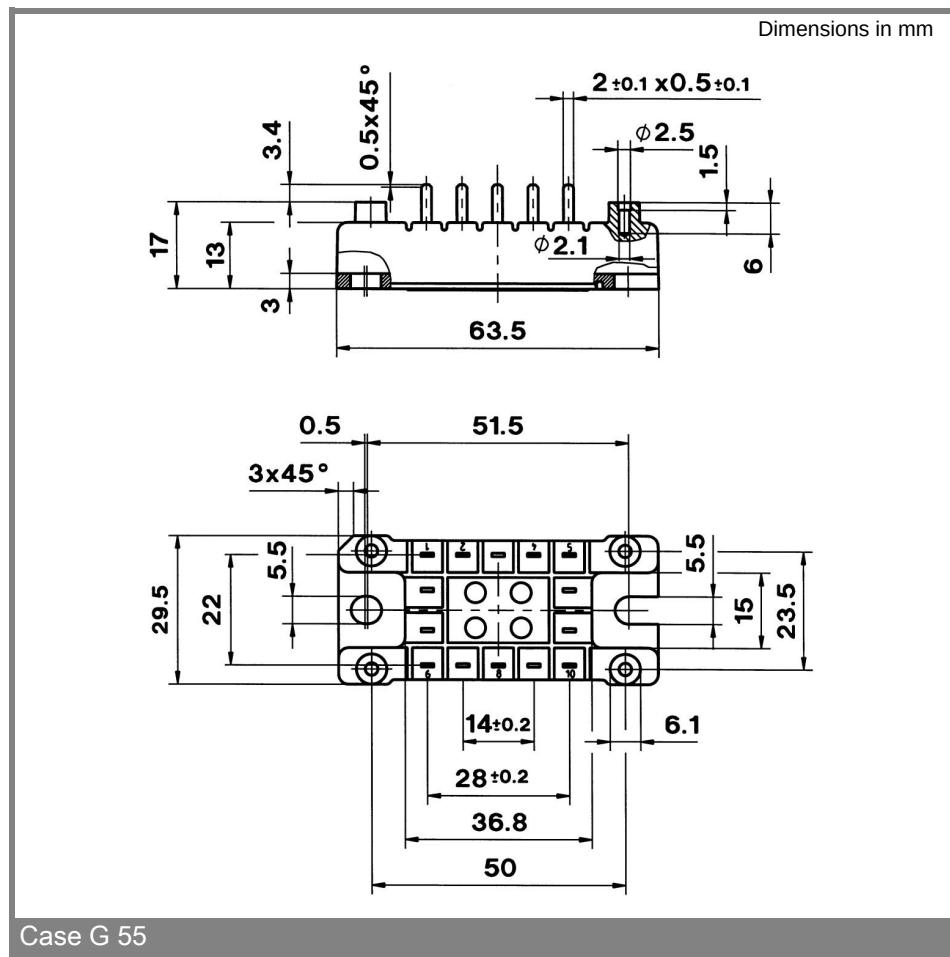
3) $T_{\text{solder}} = 250 \pm 10 \text{ }^{\circ}\text{C}$ (10 s)

V_{RSM} V	$V_{\text{RRM}}, V_{\text{DRM}}$ V	$I_D = 33 \text{ A}$ (full conduction) ($T_s = 110 \text{ }^{\circ}\text{C}$)
500	400	SKD 33/04
900	800	SKD 33/08
1300	1200	SKD 33/12
1700	1600	SKD 33/16
1900	1800	SKD 33/18

Symbol	Conditions	Values	Units
I_D	$T_s = 106 \text{ }^{\circ}\text{C}$	36	A
	$T_a = 45 \text{ }^{\circ}\text{C}$; isolated ¹⁾	4	A
	$T_a = 45 \text{ }^{\circ}\text{C}$; chassis ²⁾	16	A
	$T_a = 45 \text{ }^{\circ}\text{C}$; P5A/100 (R4A/120)	24 (25)	A
	$T_a = 35 \text{ }^{\circ}\text{C}$; P1A/120F	50	A
I_{FSM}	$T_{vj} = 25 \text{ }^{\circ}\text{C}$; 10 ms	300	A
	$T_{vj} = 150 \text{ }^{\circ}\text{C}$; 10 ms	240	A
i^2t	$T_{vj} = 25 \text{ }^{\circ}\text{C}$; 8,3 ... 10 ms	450	A ² s
	$T_{vj} = 150 \text{ }^{\circ}\text{C}$; 8,3 ... 10 ms	290	A ² s
V_F	$T_{vj} = 25 \text{ }^{\circ}\text{C}$; $I_F = 50 \text{ A}$	max. 1,6	V
$V_{(TO)}$	$T_{vj} = 150 \text{ }^{\circ}\text{C}$	max. 0,8	V
r_T	$T_{vj} = 150 \text{ }^{\circ}\text{C}$	max. 18	mΩ
I_{RD}	$T_{vj} = 25 \text{ }^{\circ}\text{C}$; $V_{DD} = V_{DRM}$; $V_{RD} = V_{RRM}$	max. 0,2	mA
	$T_{vj} = 150 \text{ }^{\circ}\text{C}$; $V_{RD} = V_{RRM}$	4	mA
$R_{th(j-s)}$	per diode	2,5	K/W
	total	0,417	K/W
	isolated ¹⁾	15,02	K/W
$R_{th(j-a)}$	chassis ²⁾	3,02	K/W
		- 40 ... + 150	$^{\circ}\text{C}$
T_{vj}		- 40 ... + 125 ³⁾	$^{\circ}\text{C}$
T_{stg}			
V_{isol}	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3600 (3000)	V
M_s	to heatsink	$2 \pm 15 \%$	Nm
M_t			
a		5 * 9,81	m/s ²
m		30	g
Case		G 55	







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